Notes:
1. When assemble the transformer, the following PCB stack sequence must be met:
   PMP20637 Winding 1 Rev B(Top) => PMP20637 Winding 3 Rev B => PMP20637 Winding 2 Rev B => PMP20637 Winding 4 Rev B (Bottom)
2. D390_x and D392_x are added on parts. (Reworked on top of R300_x and R302_x, respectively).

PCB Number: PMP20637_windings
PCB Rev: Rev B

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